

6A Avg.

35 Volts

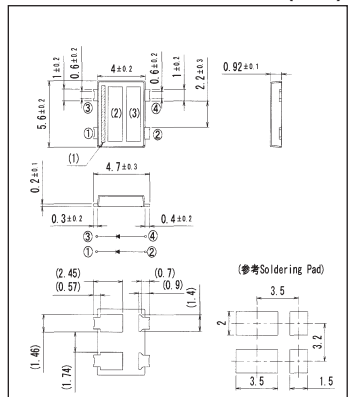
SBD

NB06QSA035

■最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	35	V
平均整流電流 Average Rectified Forward Current	I_O	$T_a=25^{\circ}C^{*2}$ $V_{RM}=15V$	3.6
		$T_l=122^{\circ}C$ T:lead Temperature $V_{RM}=15V$	6.0
実効順電流 R.M.S. Forward Current	$I_F(RMS)$	6.66	A
サージ順電流 Surge Forward Current	I_{FSM}	60 50Hz正弦半波, 1サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	-40~+150	$^{\circ}C$
保存温度範囲 Storage Temperature Range	T_{stg}	-40~+150	$^{\circ}C$

■OUTLINE DRAWING(mm)



■APPROX. NET WEIGHT:0.06 g

■電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$T_j=25^{\circ}C, V_{RM}=35V$, 一素子あたり Per Diode	—	—	2	mA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$T_j=25^{\circ}C, I_{FM}=3A$, 一素子あたり Per Diode	—	—	0.47	V
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient	—	—	60	$^{\circ}C/W$
	$R_{th(j-l)}$	接合部・リード間 Junction to Lead	—	—	7	$^{\circ}C/W$

*1 カソード共通動作による/Common Cathode Operation

*2 ガラエポ基板実装/Glass-Epoxy Substrate mounted (Soldering Lands=2.0 × 1.5 mm, 2.0 × 3.5 mm, Both Sides)

■定格・特性曲線

FIG.1 順電圧特性
FORWARD CURRENT VS. VOLTAGE

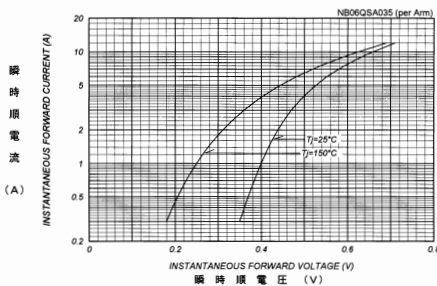


FIG.2 平均順電力損失特性
AVERAGE FORWARD POWER DISSIPATION

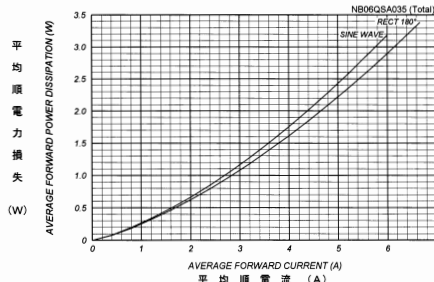


FIG.3 ピーク逆電流 - ピーク逆電圧特性
PEAK REVERSE CURRENT - PEAK REVERSE VOLTAGE

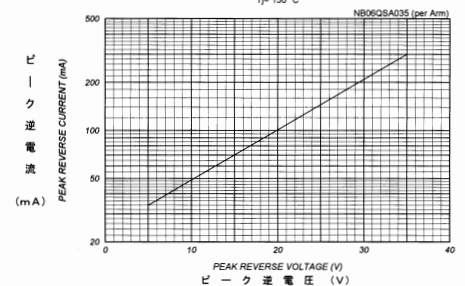


FIG.4 平均逆電力損失
AVERAGE REVERSE POWER DISSIPATION

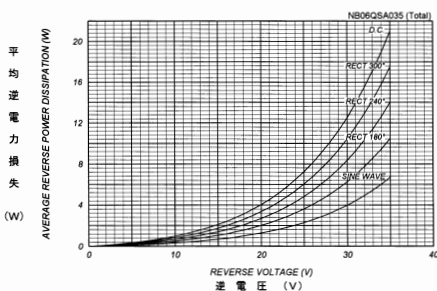


FIG.5 平均順電流 - リード温度定格
AVERAGE FORWARD CURRENT VS. LEAD TEMPERATURE

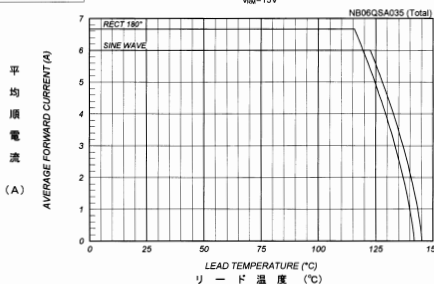


FIG.6 平均順電流 - 周囲温度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

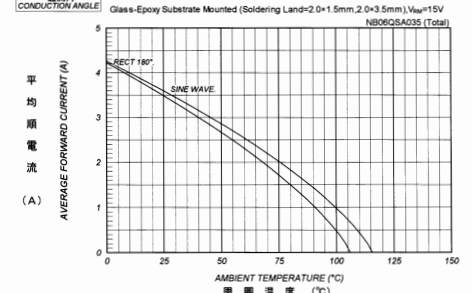


FIG.7 平均順電流 - リード温度定格
AVERAGE FORWARD CURRENT VS. LEAD TEMPERATURE

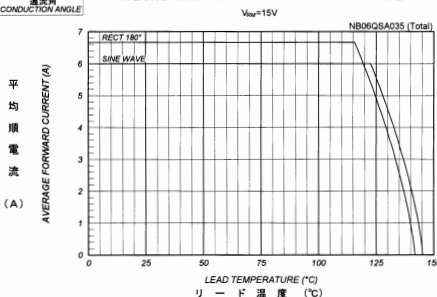


FIG.8 平均順電流 - 周囲温度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

